

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing f Claims:

1 (currently amended). A semiconductor device comprising:

a radiating plate;

a semiconductor chip bonded ~~onto~~ on one side of the radiating plate;

a resin wall ~~bonded at the lower end to the radiating plate~~ to surround the circumference of the semiconductor chip;

a conductive member extended through a lower end of the resin wall and retained by the resin wall, which is electrically connected to electrically conduct the semiconductor chip ~~to the outside~~; and

a resin lid bonded to an the upper end of the resin wall, ~~an inner lead portion of the conductive member being mounted on a base seat part formed as a part of the resin wall, and the semiconductor chip being sealed in the space blocked by the radiating plate, the resin wall and the resin lid~~

wherein the lower end of said resin wall in a first area and in the vicinity thereof are bonded to said one side and an end face of said radiating plate, and the lower end of said resin wall in a second area other than said first area and the vicinity thereof is bonded to only said one side of said radiating plate, and

said semiconductor chip is sealed in a space enclosed by said radiating plate, said resin wall and said resin lid.

2 (cancelled).

3 (original). The semiconductor device according to claim 1, wherein the resin wall is fitted to protruding parts or recessed parts provided on the radiating plate.

4 (cancelled).

5 (original). The semiconductor device according to claim 1, wherein the recessed parts are provided on the opposed side parts of the radiating plate, the protruding parts are protruded and provided on the inner surfaces of the recessed parts, and the lower end part of the resin wall is buried in the recessed parts.

6 (cancelled).

7(original). The semiconductor device according to claim 1, wherein holes are provided in the outside positions of the resin wall on the conductive member.

8 (cancelled).

9 (original). The semiconductor device according to claim 1, wherein first holes are provided in the outside positions of the resin wall on the conductive member, and second holes or cutouts are provided in the region extending through the resin wall of the conductive member.

10 (cancelled).

11 (original). The semiconductor device according to claim 9, wherein the first holes are arranged so as to overlap the space area between the second holes or cutouts when the conductive member is seen in the resin wall direction from the outside of the resin wall.

12 (cancelled).

13 (original). The semiconductor device according to claim 1, wherein a stepped part to be fitted to the inner periphery of the resin wall is provided on the resin lid.

14 (cancelled).

15 (original). The semiconductor device according to claim 13, wherein the resin lid has a vertically plane symmetric shape.

16 (cancelled).

17 (**original**). The semiconductor device according to claim 1, wherein the surface of the radiating plate surrounded by the resin wall is surface-finished by silver plating, and the other surface of the radiating plate except the part for bonding the resin wall and the inner lead part and outer lead part of the conductive member are surface finished by gold plating.

18 (**cancelled**).

19-21 (**previously withdrawn**).

22 (**previously added**). The semiconductor device according to claim 1, wherein the radiating plate has end portions formed integrally at both ends of a center portion of the radiating plate, the lower end of the resin wall is bonded to said center portion, and said end portions are exposed through the resin wall.

23 (**cancelled**).

24 (**previously added**). The semiconductor device according to claim 1, wherein said conductive member is broader on the inside of said resin wall.

25 (**cancelled**).
